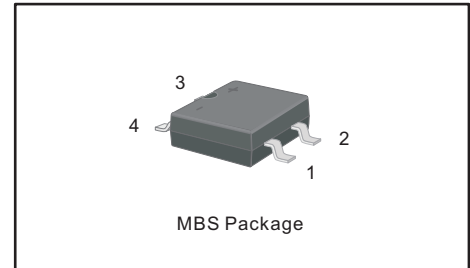


**0.8A/1.0ASURFACE MOUNT GLASS PASSIVATED BRIDGE**
**RECTIFIERFEATURES:**

Glass Passivated Chip Junction  
 Reverse Voltage - 100 to 1000 V  
 Forward Current - 0.8 A/1.0A  
 High Surge Current Capability  
 Designed for Surface Mount Application

**PINNING**

PIN	DESCRIPTION
1	Input Pin ( ~ )
2	Input Pin ( ~ )
3	Output Anode ( + )
4	Output Cathode ( - )


**MECHANICAL DATA**

- Case: MBS
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 100mg /0.0035oz

**Maximum Ratings and Electrical characteristics**

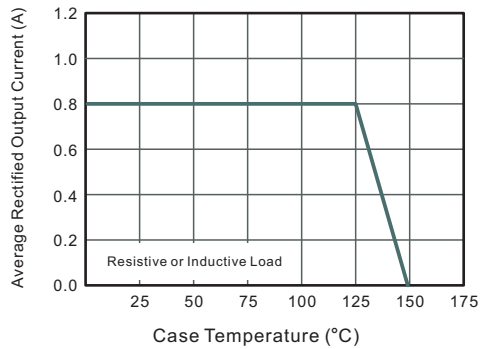
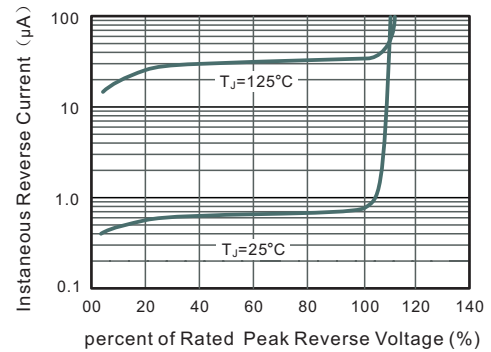
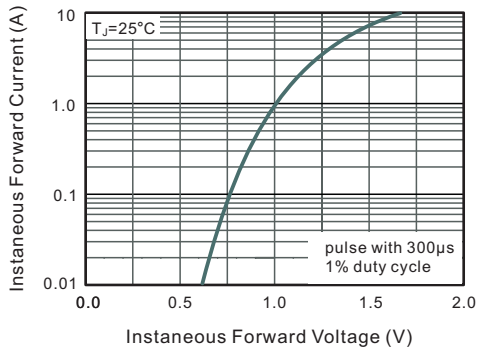
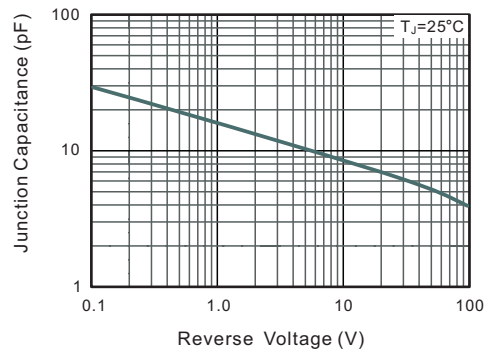
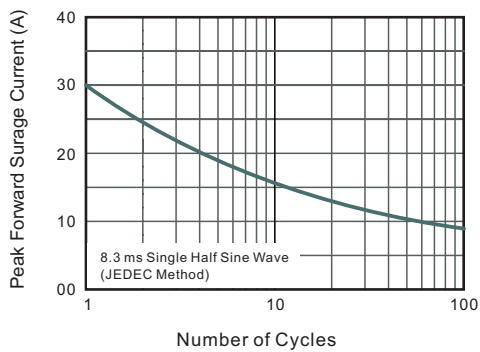
Ratings at 25 °C ambient temperature unless otherwise specified.

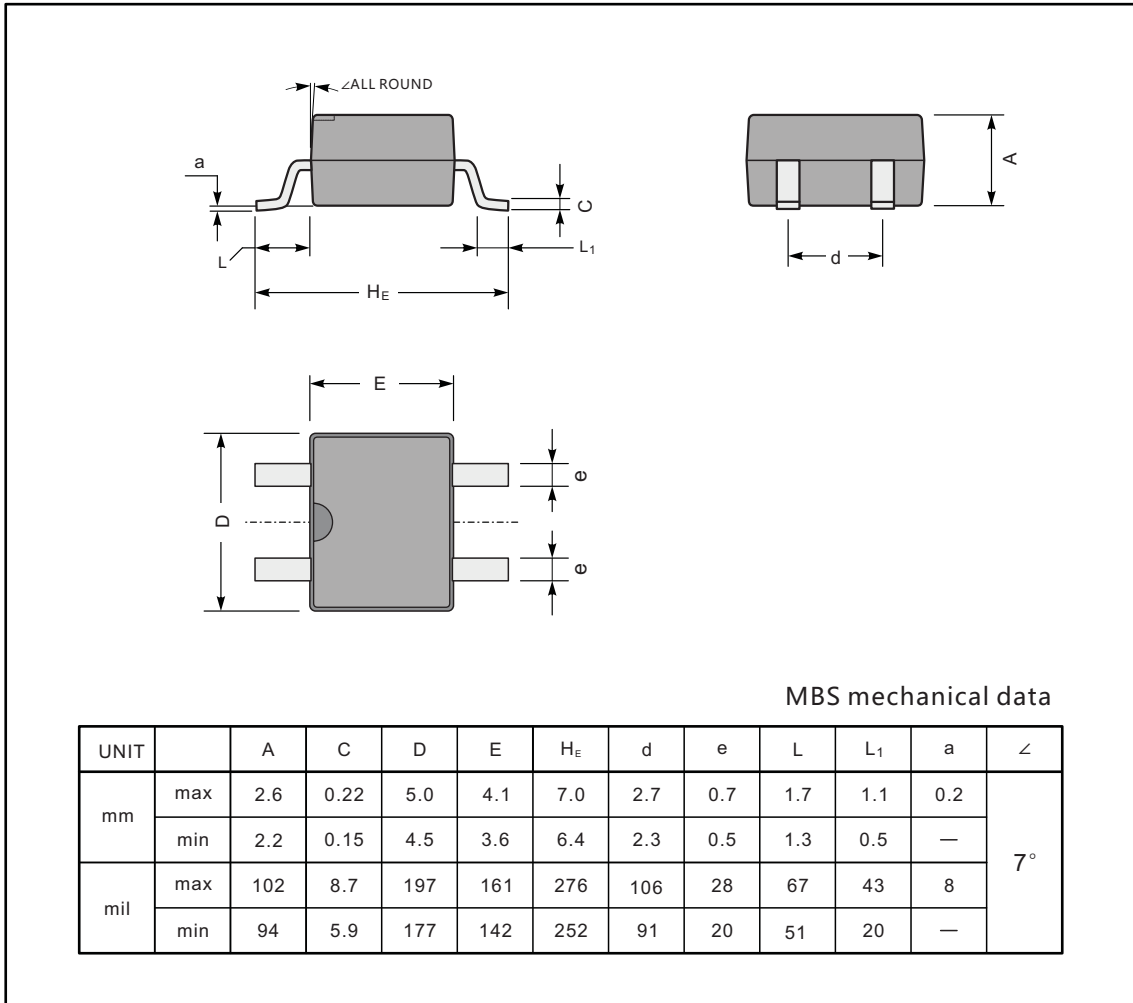
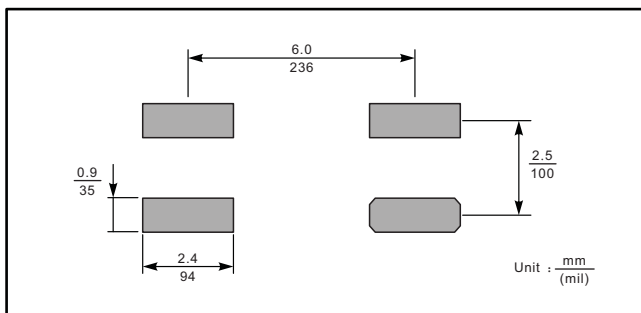
Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	MB1S	MB2S	MB4S	MB6S	MB8S	MB10S	Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	100	200	400	600	800	1000	V
Average Rectified Output Current at $T_c = 125\text{ }^\circ\text{C}$	$I_o$	0.8/1.0A						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	$I_{FSM}$	30						A
Maximum Forward Voltage at 0.4 A at 0.8 A/1.0A	$V_F$	1.0 1.1						V
Maximum DC Reverse Current at Rated DC Blocking Voltage @ $T_A=25\text{ }^\circ\text{C}$ @ $T_A=125\text{ }^\circ\text{C}$	$I_R$	5 40						$\mu\text{A}$
Typical Junction Capacitance ( Note1 )	$C_j$	13						pF
Typical Thermal Resistance ( Note2 )	$R_{\theta JA}$ $R_{\theta JC}$	90 32						$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55 ~ +150						$^\circ\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4×1.5"×1.5" ( 3.81×3.81 cm ) copper pad.

**Fig.1 Average Rectified Output Current Derating Curve**

**Fig.2 Typical Reverse Characteristics**

**Fig.3 Typical Instantaneous Forward Characteristics**

**Fig.4 Typical Junction Capacitance**

**Fig.5 Maximum Non-Repetitive Peak Forward Surge Current**


**PACKAGE OUTLINE**
**Plastic surface mounted package; 4 leads**
**MBS**

**The recommended mounting pad size**

**Marking**

Type number	Marking code
MB1S	MB1S
MB2S	MB2S
MB4S	MB4S
MB6S	MB6S
MB8S	MB8S
MB10S	MB10S